

## Single-Phase Full-Wave Motor Driver with Built-in Hall Sensor

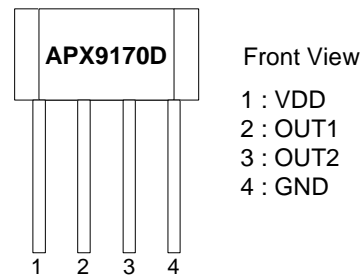
### Features

- **On-Chip Hall Sensor**
- **High Sensitivity Hall Effect Sensor IC:  $\pm 15\text{G}$ (Type.)**
- **Built-in Lock Protection and Auto Restart Function**
- **Built-In Thermal Protection Circuit**
- **4 Pin TO92-M4 Package**
- **Lead Free and Green Devices Available (RoHS Compliant)**

### General Description

The APX9170D is an integrated Hall Effect Sensor IC designed for electric commutation of single-phase DC brushless motor applications. The device is built-in lock protection. When fan is locked, the device will enter the lock protection mode. It is also with thermal shutdown function. The APX9170D is available in a low cost TO92-M4 package.

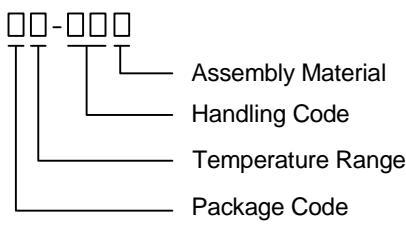
### Pin Description



### Applications

- **Brushless DC Fans**
- **Brushless DC Motors**

### Ordering and Marking Information

<p>APX9170D    □□-□□□</p>  <ul style="list-style-type: none"> <li>Assembly Material</li> <li>Handling Code</li> <li>Temperature Range</li> <li>Package Code</li> </ul>	<p>Package Code E : TO - 92M4</p> <p>Temperature Range I : -40 to 105 °C</p> <p>Handling Code PB : Plastic Bag</p> <p>Assembly Material G : Halogen and Lead Free Device</p>	
<p>APX9170D E :</p> <table border="1" style="display: inline-table; border-collapse: collapse;"> <tr> <td style="padding: 2px;">                 APX 9170 XXXXX             </td> </tr> </table>	APX 9170 XXXXX	<p>XXXXX - Date Code</p>
APX 9170 XXXXX		

Note: ANPEC lead-free products contain molding compounds/die attach materials and 100% matte tin plate termination finish; which are fully compliant with RoHS. ANPEC lead-free products meet or exceed the lead-free requirements of IPC/JEDEC J-STD-020D for MSL classification at lead-free peak reflow temperature. ANPEC defines "Green" to mean lead-free (RoHS compliant) and halogen free (Br or Cl does not exceed 900ppm by weight in homogeneous material and total of Br and Cl does not exceed 1500ppm by weight).

ANPEC reserves the right to make changes to improve reliability or manufacturability without notice, and advise customers to obtain the latest version of relevant information to verify before placing orders.

**Absolute Maximum Ratings** ( $T_A=25^{\circ}\text{C}$  unless otherwise noted) (Note 1)

Symbol	Parameter	Rating	Unit
$V_{DD}$	VDD Pin Supply Voltage (VDD to GND)	-0.3 to 20	V
$V_{OUT}$	Output Pin (OUT1, OUT2) Output Voltage	-0.3 to 20	V
$I_{OUT}$	Output Pin (OUT1, OUT2) Maximum Output Current – Continuous Hold	250 500	mA
$T_J$	Maximum Junction Temperature	150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature	-65 to 150	$^{\circ}\text{C}$
$T_{SOR}$	Maximum Lead Soldering Temperature, 10 Seconds	260	$^{\circ}\text{C}$

Note1: Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**Thermal Characteristics**

Symbol	Parameter	Typical Value	Unit
$R_{THJA}$	Thermal Resistance-Junction to Ambient (Note 2) TO-92M4	131	$^{\circ}\text{C}/\text{W}$
$P_D$	Power Dissipation, $T_A = 25^{\circ}\text{C}$ TO-92M4	950	mW

Note 2 : The maximum allowable power dissipation at any  $T_A$  (ambient temperature) is calculated using:  $P_D (\text{max}) = (T_J - T_A) / \theta_{JA}$ ;  $T_J = 150^{\circ}\text{C}$ . Exceeding the maximum allowable power dissipation will result in excessive die temperature.

**Recommended Operating Conditions**

Symbol	Parameter	Range	Unit
$V_{DD}$	VDD Supply Voltage	2.5 to 17	V
$T_A$	Operating Ambient Temperature	-40 to 105	$^{\circ}\text{C}$
$T_J$	Junction Temperature	-40 to 125	$^{\circ}\text{C}$

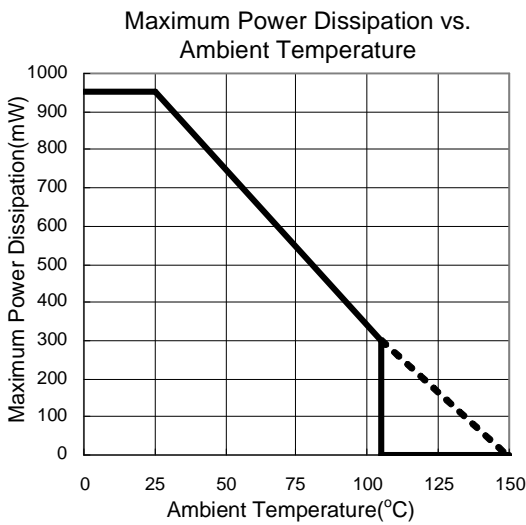
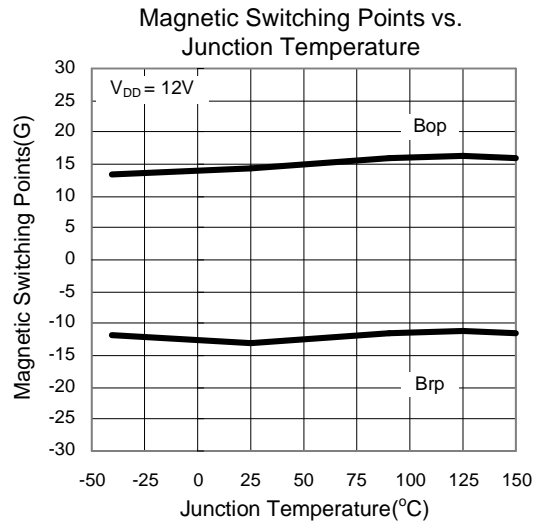
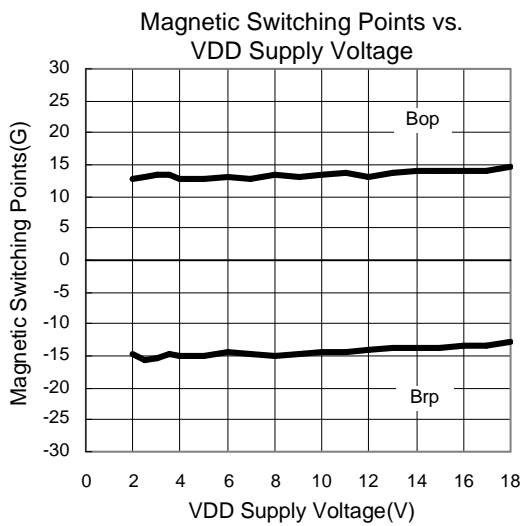
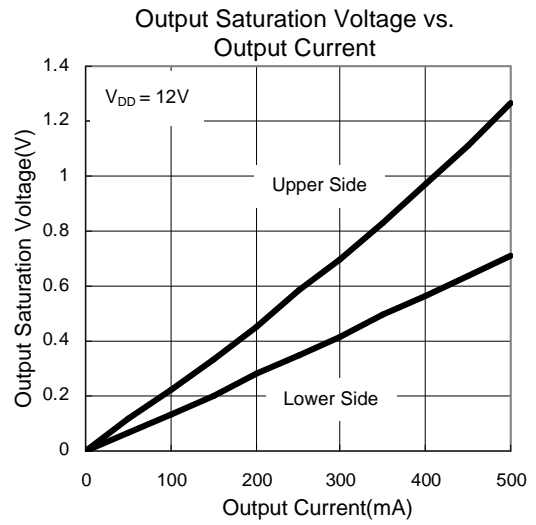
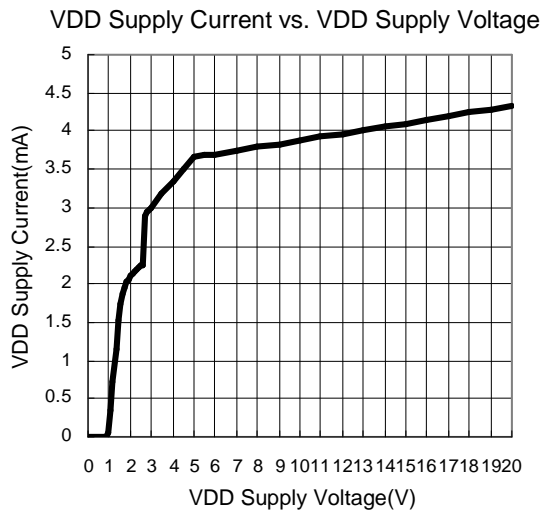
**Electrical Characteristics** ( $T_A=25^{\circ}\text{C}$ ,  $V_{DD}=12\text{V}$  unless otherwise noted)

Symbol	Parameter	Test Conditions	APX9170D			Unit
			Min.	Typ.	Max.	
$I_{DD}$	VDD Supply Current	$V_{DD}=17\text{V}$ , no load		4.5	7	mA
$V_O$	Output Driver Saturation Voltage	$I_{OUT}=200\text{mA}$ , Upper and Lower total	-	0.8	1.2	V
$T_{ON}$	Lock Detection On Time		-	0.4	-	sec
$T_{OFF}$	Lock Detection Off Time		-	4	-	sec
OTS	Over Temperature Shutdown Threshold		-	165	-	$^{\circ}\text{C}$
	Over Temperature Shutdown Hysteresis		-	30	-	$^{\circ}\text{C}$

## Magnetic Characteristics (T<sub>A</sub>=25°C, V<sub>DD</sub>=12V unless otherwise noted)

Symbol	Parameter	Test Conditions	APX9170D			Unit
			Min.	Typ.	Max.	
Bop	Magnetic Operation Point		5	15	30	Gauss
Brp	Magnetic Release Point		-30	-15	-5	Gauss
Bhys	Magnetic Hysteresis		-	30	-	Gauss

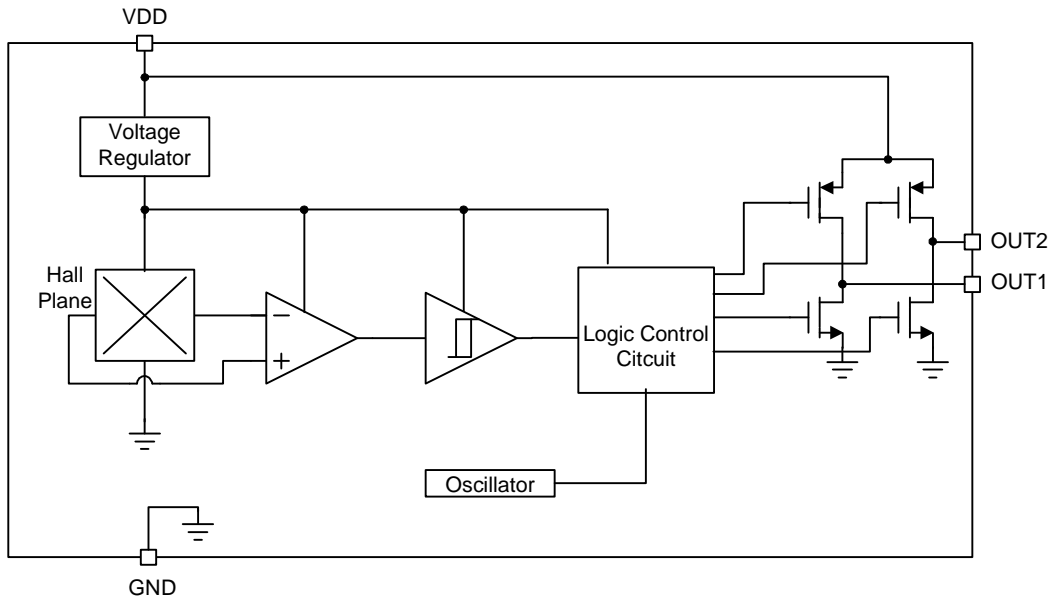
Typical Operating Characteristics



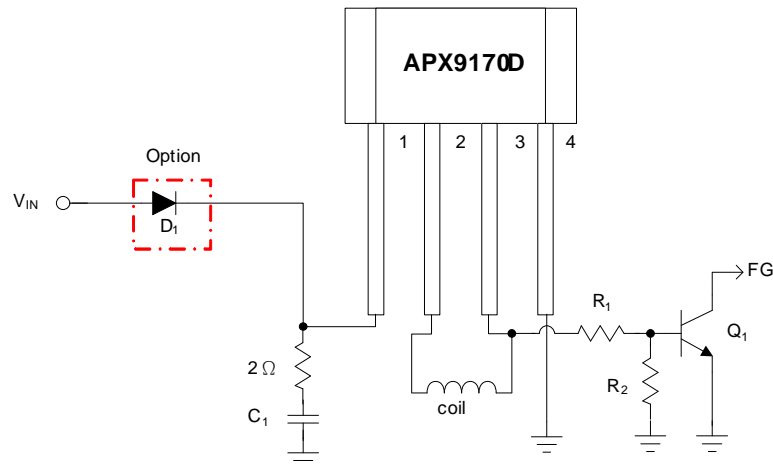
## Pin Description

PIN		FUNCTION
NO.	NAME	
1	VDD	Supply Voltage Input.
2	OUT1	H-bridge output connection.
3	OUT2	H-bridge output connection.
4	GND	Ground of the IC.

Block Diagram



Typical Application Circuit

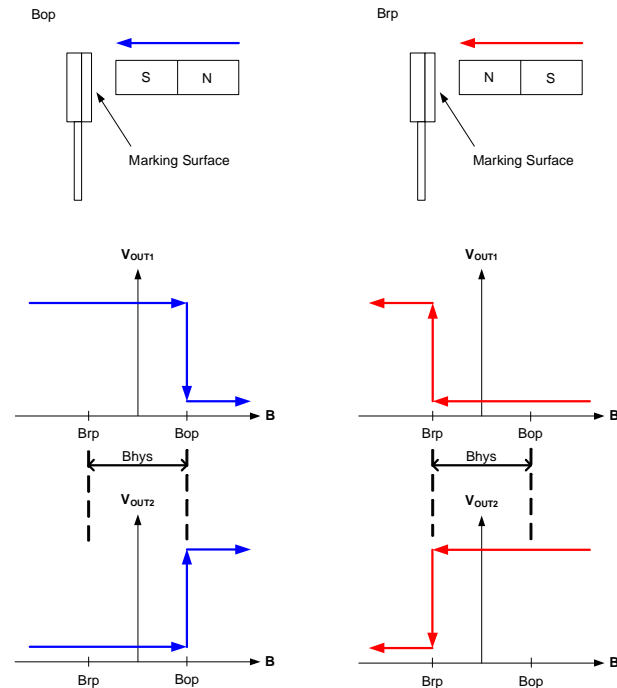


Notes: D<sub>1</sub> is to protect IC when reverse power input  
 C<sub>1</sub> must use at least 1μF/25V capacitor and place as close to IC as possible .  
 R<sub>1</sub>, R<sub>2</sub> and Q<sub>1</sub> are for FG function application circuit.

## Function Description

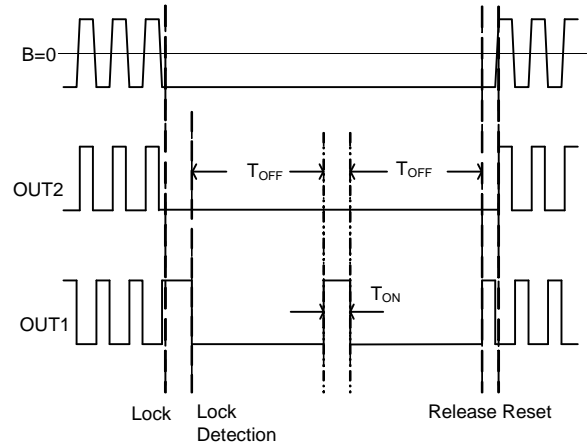
### Output Switch Principle

The APX9170D built in a Hall-effect sensor plane to sense the vertical magnetic flux density (B). There are two output drivers in APX9170D to drive single-phase DC brushless motor. When the N pole magnetic field close to the IC marking surface and the magnetic flux density higher than operate point (Bop), the OUT1 pin output will turn to LOW and the OUT2 pin output will turn to HIGH. When the N pole magnetic field far away the IC marking surface and S pole magnetic field close to the IC marking surface until the magnetic flux density higher than release point (Brp), the OUT1 pin output will turn HIGH and the OUT2 pin output will turn LOW.



### Lockup Protection and Automatic Restart

The APX9170D detects the rotation of the motor by internal hall sensor signal, and adjusts lock detection ON time ( $T_{ON}$ ) and lock detection OFF time ( $T_{OFF}$ ) by internal counter.

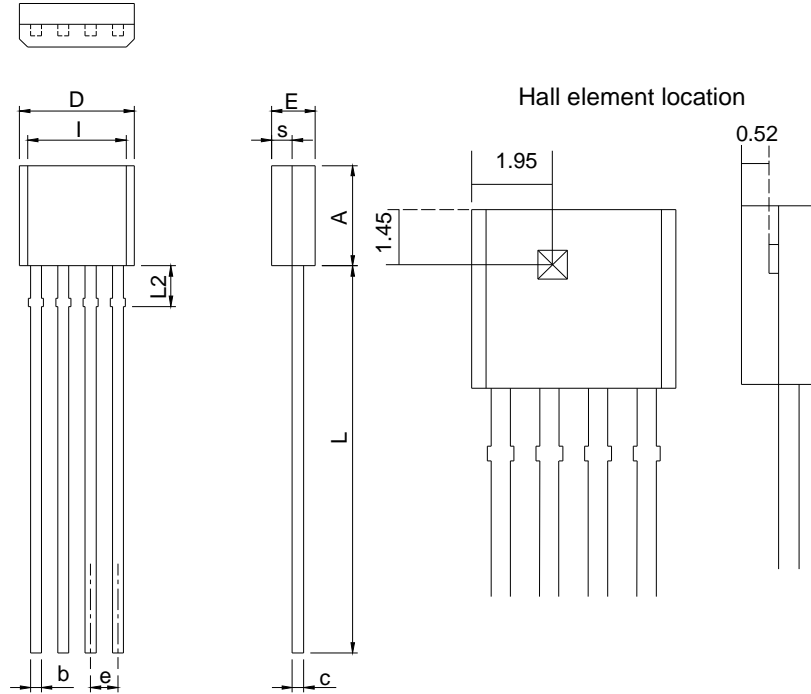


### Thermal Protection

The APX9170D has a thermal protection. When the internal junction temperature reaches 165°C, the output devices will be switched off. When the IC's junction temperature cools by 30°C, the thermal sensor will turn the output devices on again, resulting in a pulsed output during continuous thermal protection.

Package Information

TO-92M4

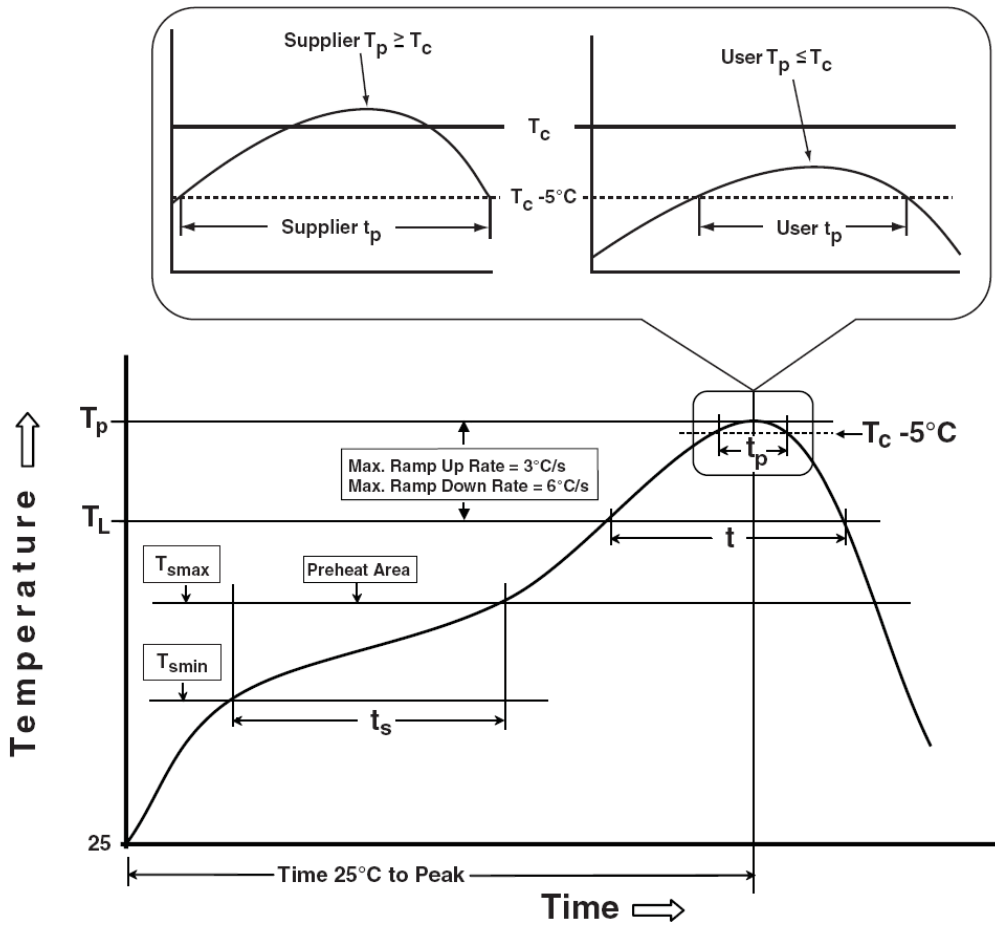


Sensitive Area (0.286x0.286mm<sup>2</sup>)  
 Position of Hall Sensor  
 reference to the top-left of package  
 x= 1.45±0.1mm  
 y= 1.95±0.1mm

SYMBOL	TO-92M4			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	3.45	3.75	0.136	0.148
b	0.31	0.56	0.012	0.022
c	0.35	0.51	0.014	0.020
D	4.98	5.32	0.196	0.209
e	1.27 BSC		0.050 BSC	
E	1.40	1.80	0.055	0.071
I	3.78	4.67	0.149	0.184
L	13.50	15.80	0.531	0.622
L2	1.34	1.65	0.053	0.065
s	0.50	0.90	0.020	0.035



Classification Profile



Classification Reflow Profiles

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
<b>Preheat &amp; Soak</b>		
Temperature min ( $T_{smin}$ )	100 °C	150 °C
Temperature max ( $T_{smax}$ )	150 °C	200 °C
Time ( $T_{smin}$ to $T_{smax}$ ) ( $t_s$ )	60-120 seconds	60-120 seconds
Average ramp-up rate ( $T_{smax}$ to $T_p$ )	3 °C/second max.	3°C/second max.
Liquidous temperature ( $T_L$ )	183 °C	217 °C
Time at liquidous ( $t_l$ )	60-150 seconds	60-150 seconds
Peak package body Temperature ( $T_p$ )*	See Classification Temp in table 1	See Classification Temp in table 2
Time ( $t_p$ )** within 5°C of the specified classification temperature ( $T_c$ )	20** seconds	30** seconds
Average ramp-down rate ( $T_p$ to $T_{smax}$ )	6 °C/second max.	6 °C/second max.
Time 25°C to peak temperature	6 minutes max.	8 minutes max.

\* Tolerance for peak profile Temperature ( $T_p$ ) is defined as a supplier minimum and a user maximum.  
 \*\* Tolerance for time at peak profile temperature ( $t_p$ ) is defined as a supplier minimum and a user maximum.

**Classification Reflow Profiles (Cont.)**

Table 1. SnPb Eutectic Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

Table 2. Pb-free Process – Classification Temperatures (Tc)

Package Thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350-2000	Volume mm <sup>3</sup> >2000
<1.6 mm	260 °C	260 °C	260 °C
1.6 mm – 2.5 mm	260 °C	250 °C	245 °C
≥2.5 mm	250 °C	245 °C	245 °C

**Reliability Test Program**

Test item	Method	Description
SOLDERABILITY	JESD-22, B102	5 Sec, 245°C
HOLT	JESD-22, A108	1000 Hrs, Bias @ T <sub>j</sub> =125°C
PCT	JESD-22, A102	168 Hrs, 100%RH, 2atm, 121°C
TCT	JESD-22, A104	500 Cycles, -65°C~150°C
HBM	MIL-STD-883-3015.7	VHBM ≥ 2KV
MM	JESD-22, A115	VMM ≥ 200V
Latch-Up	JESD 78	10ms, 1 <sub>tr</sub> ≥ 100mA

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